

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An active matrix type display device comprising:
a plurality of pixels arranged in matrix ~~[[form]]~~ formed over a substrate;
a driver circuit for driving the plurality of pixels over said substrate, said driver circuit including at least one buffer circuit;
at least two transistors in said at least one buffer circuit;
~~a common gate wiring connected with said at least two transistors at gate electrodes of said at least two transistors~~ electrode adjacent to channel-forming regions of said at least two transistors;
~~a common source wiring connected with said at least two transistors at one of source and drain of each of said at least two transistors~~ electrode connected with source regions of said at least two transistors; and
~~a common drain wiring connected with said at least two transistors at the other of the source and drain of each of said at least two transistors~~ electrode connected with drain regions of said at least two transistors,
wherein said at least two transistors are connected with each other in parallel by ~~the connections of~~ through said common gate ~~wiring~~ electrode, said common source ~~wiring~~ electrode, and said common drain ~~wiring~~ electrode with ~~said at least two transistors, [[and]]~~
wherein said channel-forming regions of said at least two transistors are separately provided in at least two separate semiconductor layers respectively, and wherein said channel-forming regions are formed on a same insulating surface.

2. (Currently Amended) An active matrix type display device comprising:

a plurality of pixels arranged in matrix ~~[[form]]~~ formed over a substrate;

a driver circuit for driving the plurality of pixels over said substrate;

at least two transistors in said driver circuit;

~~a common gate wiring connected with said at least two transistors at gate electrodes of said at least two transistors~~ electrode adjacent to channel-forming regions of said at least two transistors;

~~a common source wiring connected with said at least two transistors at one of source and drain of each of said at least two transistors~~ electrode connected with source regions of said at least two transistors; and

~~a common drain wiring connected with said at least two transistors at the other of the source and drain of each of said at least two transistors~~ electrode connected with drain regions of said at least two transistors,

wherein said at least two transistors are connected with each other in parallel by ~~the connections of~~ through said common gate wiring electrode, said common source wiring electrode, and said common drain wiring electrode with ~~said at least two transistors~~, and

wherein channel-forming regions of said at least two transistors are separately provided in at least two separate semiconductor layers respectively, and wherein said channel-forming regions are formed on a same insulating surface.

3. (Currently Amended) An active matrix type display device comprising:

a plurality of pixels arranged in matrix ~~[[form]]~~ formed over a substrate;

a driver circuit for driving the plurality of pixels over said substrate, said driver circuit including at least one buffer circuit;

at least two transistors in said at least one buffer circuit;

~~a common gate wiring connected with said at least two transistors at gate electrodes of said at least two transistors~~ electrode adjacent to channel-forming regions of said at least two transistors;

~~a common source wiring connected with said at least two transistors at one of source and drain of each of said at least two transistors~~ electrode connected with source regions of said at least two transistors; and

~~a common drain wiring connected with said at least two transistors at the other of the source and drain of each of said at least two transistors~~ electrode connected with drain regions of said at least two transistors,

wherein said at least two transistors are connected with each other in parallel by ~~the connections of~~ through said common gate wiring electrode, said common source wiring electrode, and said common drain wiring electrode ~~with said at least two transistors, and~~

wherein said channel-forming regions of said at least two transistors are separately provided in at least two separate semiconductor layers respectively, ~~[[and]]~~ each of said channel-forming regions not having linear defects or surface defects, and wherein said channel-forming regions are formed on a same insulating surface.

4.-7. (Canceled)

8. (Currently Amended) An active matrix type display device comprising:

a plurality of pixels arranged in matrix ~~[[form]]~~ formed over a substrate;

a driver circuit for driving the plurality of pixels over said substrate;

at least two transistors in said driver circuit ~~in said active matrix type display device;~~

~~a common gate wiring connected with said at least two transistors at gate electrodes of said at least two transistors~~ electrode adjacent to channel-forming regions of said at least two transistors;

~~a common source wiring connected with said at least two transistors at one of source and drain of each of said at least two transistors~~ electrode connected with source regions of said at least two transistors;

~~a common drain wiring connected with said at least two transistors at the other of the source and drain of each of said at least two transistors~~ electrode connected with drain regions of said at least two transistors,

wherein said at least two transistors are connected with each other in parallel by ~~the connections of~~ through said common gate ~~wiring~~ electrode, said common source wiring electrode and said common drain wiring electrode ~~with said at least two transistors, and~~

wherein said channel-forming regions of said at least two transistors are separately provided in at least two separate semiconductor layers respectively, [[and]] each of said channel-forming regions not having linear defects or surface defects, and wherein said channel-forming regions are formed on a same insulating surface.

9.-10. (Canceled)

11. (Previously Presented) The device of claim 1 wherein said active matrix type display device comprises a memory.

12. (Previously Presented) The device of claim 1 wherein said active matrix type display device comprises a decoder.

13. (Previously Presented) The device of claim 1 wherein said active matrix type display device comprises a display system.

14. (Previously Presented) The device of claim 2, wherein said active matrix type display device comprises a memory.

15. (Canceled)

16. (Previously Presented) The device of claim 2 wherein said active matrix type display device comprises a display system.

17. (Previously Presented) The device of claim 3 wherein said active matrix type display device comprises a memory.

18. (Previously Presented) The device of claim 3 wherein said active matrix type display device comprises a decoder.

19. (Previously Presented) The device of claim 3 wherein said active matrix type display device comprises a display system.

20.-31. (Canceled)

32. (Previously Presented) The device of claim 8 wherein said active matrix type display device comprises a memory.

33. (Previously Presented) The device of claim 8 wherein said active matrix type display device comprises a decoder.

34. (Previously Presented) The device of claim 8 wherein said active matrix type display device comprises a display system.

35.-37. (Canceled)

38. (Previously Presented) The device of claim 58 wherein ratio (W/W_0) between width W_0 of a spectrum at a position at half of a Raman spectrum intensity for a monocrystalline silicon wafer and a width W of a spectrum at a position at half of a

Raman spectrum intensity for said regions which can be regarded as being effectively monocrystalline is 2.0 or less.

39. (Previously Presented) The device of claim 58 wherein ratio (I/I_0) between a Raman spectrum intensity I_0 of a monocrystalline silicon wafer and a Raman spectrum intensity I of said regions which can be regarded as being effectively monocrystalline is 0.8 or more.

40. (Previously Presented) The device of claim 59 wherein ratio (W/W_0) between width W_0 of a spectrum at a position at half of a Raman spectrum intensity for a monocrystalline silicon wafer and a width W of a spectrum at a position at half of a Raman spectrum intensity for said regions which can be regarded as being effectively monocrystalline is 2.0 or less.

41. (Previously Presented) The device of claim 59 wherein ratio (I/I_0) between a Raman spectrum intensity I_0 of a monocrystalline silicon wafer and a Raman spectrum intensity I of said regions which can be regarded as being effectively monocrystalline is 0.8 or more.

42. (Previously Presented) The device of claim 60 wherein ratio (W/W_0) between width W_0 of a spectrum at a position at half of a Raman spectrum intensity for a monocrystalline silicon wafer and a width W of a spectrum at a position at half of a Raman spectrum intensity for said regions which can be regarded as being effectively monocrystalline is 2.0 or less.

43. (Previously Presented) The device of claim 60 wherein ratio (I/I_0) between a Raman spectrum intensity I_0 of a monocrystalline silicon wafer and a Raman spectrum intensity I of said regions which can be regarded as being effectively monocrystalline is

0.8 or more.

44.-51. (Canceled)

52. (Previously Presented) The device of claim 65 wherein ratio (W/W_0) between width W_0 of a spectrum at a position at half of a Raman spectrum intensity for a monocrystalline silicon wafer and a width W of a spectrum at a position at half of a Raman spectrum intensity for said regions which can be regarded as being effectively monocrystalline is 2.0 or less.

53. (Previously Presented) The device of claim 65 wherein ratio (I/I_0) between a Raman spectrum intensity I_0 of a monocrystalline silicon wafer and a Raman spectrum intensity I of said regions which can be regarded as being effectively monocrystalline is 0.8 or more.

54.-57. (Canceled)

58. (Previously Presented) The device of claim 1 wherein at least said channel-forming regions of said at least two transistors are provided in regions which can be regarded as being effectively monocrystalline, and wherein said regions which can be regarded as being effectively monocrystalline comprise silicon.

59. (Previously Presented) The device of claim 2 wherein at least said channel-forming regions of said at least two transistors are provided in regions which can be regarded as being effectively monocrystalline, and wherein said regions which can be regarded as being effectively monocrystalline comprise silicon.

60. (Previously Presented) The device of claim 3 wherein at least said channel-

forming regions of said at least two transistors are provided in regions which can be regarded as being effectively monocrystalline, and wherein said regions which can be regarded as being effectively monocrystalline comprise silicon.

61.-64. (Canceled)

65. (Previously Presented) The device of claim 8 wherein at least said channel-forming regions of said at least two transistors are provided in regions which can be regarded as being effectively monocrystalline, and wherein said regions which can be regarded as being effectively monocrystalline comprise silicon.

66.-70. (Canceled)

71. (Previously Presented) The device of claim 1 wherein said active matrix type display device is a liquid crystal display device.

72. (Previously Presented) The device of claim 2 wherein said active matrix type display device is a liquid crystal display device.

73. (Previously Presented) The device of claim 3 wherein said active matrix type display device is a liquid crystal display device.

74. (Canceled)

75. (Previously Presented) The device of claim 8 wherein said active matrix type display device is a liquid crystal display device.

76.-77. (Canceled)

78. (Currently Amended) The device of claim 1 wherein said ~~channel-forming region has~~ channel-forming regions have point defects.

79. (Currently Amended) The device of claim 2 wherein said ~~channel-forming region has~~ channel-forming regions have point defects.

80. (Currently Amended) The device of claim 3 wherein said ~~channel-forming region has~~ channel-forming regions have point defects.

81. (Currently Amended) The device of claim 8 wherein said ~~channel-forming region has~~ channel-forming regions have point defects.

82.-99. (Canceled)

100. (Previously Presented) The device of claim 1, wherein each of said channel-forming regions contains carbon and nitrogen at a concentration of $5 \times 10^{18} \text{ cm}^{-3}$ or less, respectively, and contains oxygen at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.

101. (Previously Presented) The device of claim 2, wherein each of said channel-forming regions contains carbon and nitrogen at a concentration of $5 \times 10^{18} \text{ cm}^{-3}$ or less, respectively, and contains oxygen at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.

102. (Previously Presented) The device of claim 3, wherein each of said channel-forming regions contains carbon and nitrogen at a concentration of $5 \times 10^{18} \text{ cm}^{-3}$ or less, respectively, and contains oxygen at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.

103. (Previously Presented) The device of claim 8, wherein each of said

channel-forming regions contains carbon and nitrogen at a concentration of $5 \times 10^{18} \text{ cm}^{-3}$ or less, respectively, and contains oxygen at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.

104.-121. (Canceled)

122. (New) An active matrix type display device comprising:

a plurality of pixels over a substrate;

a driver circuit for driving the plurality of pixels over said substrate, wherein said driver circuit comprises a buffer circuit, wherein said buffer circuit comprises a first thin film transistor and a second thin film transistor, wherein said first thin film transistor comprises a first semiconductor layer and said second thin film transistor comprises a second semiconductor layer, and wherein said first semiconductor layer and said second semiconductor layer are formed on a same insulating surface;

a common gate electrode adjacent to said first semiconductor layer and said second semiconductor layer;

a common source electrode electrically connected with said first semiconductor layer and said second semiconductor layer; and

a common drain electrode electrically connected with said first semiconductor layer and said second semiconductor layer,

wherein said first thin film transistor and said second thin film transistor are connected in parallel with each other through said common gate electrode, said common source electrode, and said common drain electrode, and

wherein said first semiconductor layer and said second semiconductor layer are separately provided with each other.

123. (New) The device of claim 122, wherein said common source electrode and said common drain electrode are directly in contact with said first semiconductor layer and said second semiconductor layer.

124. (New) The device of claim 122, wherein said common gate electrode, said common source electrode, and said common drain electrode extend in parallel with each other.

125. (New) The device of claim 122, wherein said common gate electrode is formed over said first semiconductor layer and said second semiconductor layer.

126. (New) The device of claim 122, wherein said first semiconductor layer and said second semiconductor layer comprise monocrystalline silicon.

127. (New) The device of claim 122, wherein said active matrix type display device is a liquid crystal display device.

128. (New) An active matrix type display device comprising:

- a plurality of pixels over a substrate;

- a driver circuit for driving the plurality of pixels over said substrate, wherein said driver circuit comprises a first thin film transistor and a second thin film transistor, wherein said first thin film transistor comprises a first semiconductor layer and said second thin film transistor comprises a second semiconductor layer, and wherein said first semiconductor layer and said second semiconductor layer are formed on a same insulating surface;

- a common gate electrode adjacent to said first semiconductor layer and said second semiconductor layer;

- a common source electrode electrically connected with said first semiconductor layer and said second semiconductor layer; and

- a common drain electrode electrically connected with said first semiconductor layer and said second semiconductor layer,

wherein said first thin film transistor and said second thin film transistor are connected in parallel with each other through said common gate electrode, said common source electrode, and said common drain electrode, and

wherein said first semiconductor layer and said second semiconductor layer are separately provided with each other.

129. (New) The device of claim 128, wherein said common source electrode and said common drain electrode are directly in contact with said first semiconductor layer and said second semiconductor layer.

130. (New) The device of claim 128, wherein said common gate electrode, said common source electrode, and said common drain electrode extend in parallel with each other.

131. (New) The device of claim 128, wherein said common gate electrode is formed over said first semiconductor layer and said second semiconductor layer.

132. (New) The device of claim 128, wherein said first semiconductor layer and said second semiconductor layer comprise monocrystalline silicon.

133. (New) The device of claim 128, wherein said active matrix type display device is a liquid crystal display device.

134. (New) An active matrix type display device comprising:
a plurality of pixels over a substrate;
a driver circuit for driving the plurality of pixels over said substrate, wherein said driver circuit comprises a buffer circuit, wherein said buffer circuit comprises a first thin film transistor and a second thin film transistor, and wherein said first thin film transistor

comprises a first semiconductor layer and said second thin film transistor comprises a second semiconductor layer;

a common gate electrode adjacent to said first semiconductor layer and said second semiconductor layer;

a common source electrode electrically connected with said first semiconductor layer and said second semiconductor layer; and

a common drain electrode electrically connected with said first semiconductor layer and said second semiconductor layer,

wherein said first thin film transistor and said second thin film transistor are connected in parallel with each other through said common gate electrode, said common source electrode, and said common drain electrode, and

wherein said first semiconductor layer and said second semiconductor layer are not in direct contact with each other.

135. (New) The device of claim 134, wherein said common source electrode and said common drain electrode are directly in contact with said first semiconductor layer and said second semiconductor layer.

136. (New) The device of claim 134, wherein said common gate electrode, said common source electrode, and said common drain electrode extend in parallel with each other.

137. (New) The device of claim 134, wherein said common gate electrode is formed over said first semiconductor layer and said second semiconductor layer.

138. (New) The device of claim 134, wherein said first semiconductor layer and said second semiconductor layer comprise monocrystalline silicon.

139. (New) The device of claim 134, wherein said active matrix type display device is a liquid crystal display device.

140. (New) An active matrix type display device comprising:

a plurality of pixels over a substrate;

a driver circuit for driving the plurality of pixels over said substrate, wherein said driver circuit comprises a first thin film transistor and a second thin film transistor, and wherein said first thin film transistor comprises a first semiconductor layer and said second thin film transistor comprises a second semiconductor layer;

a common gate electrode adjacent to said first semiconductor layer and said second semiconductor layer;

a common source electrode electrically connected with said first semiconductor layer and said second semiconductor layer; and

a common drain electrode electrically connected with said first semiconductor layer and said second semiconductor layer,

wherein said first thin film transistor and said second thin film transistor are connected in parallel with each other through said common gate electrode, said common source electrode, and said common drain electrode, and

wherein said first semiconductor layer and said second semiconductor layer are not in direct contact with each other.

141. (New) The device of claim 140, wherein said common source electrode and said common drain electrode are directly in contact with said first semiconductor layer and said second semiconductor layer.

142. (New) The device of claim 140, wherein said common gate electrode, said common source electrode, and said common drain electrode extend in parallel with each other.

143. (New) The device of claim 140, wherein said common gate electrode is formed over said first semiconductor layer and said second semiconductor layer.

144. (New) The device of claim 140, wherein said first semiconductor layer and said second semiconductor layer comprise monocrystalline silicon.

145. (New) The device of claim 140, wherein said active matrix type display device is a liquid crystal display device.